

PCB LAYOUT (COMPONENT SIDE VIEW)

MATERIAL:

1. HOUSING MATERIAL :GLASS FILLED POLYESTER UL94V-0.
2. CONTACT MATERIAL :PHOSPHOR BRONZE t=0.35mm
3. PLATING :SELECTING GOLD PLATING
- 1u"~50u"OVER NICKEL IN CONTACT AREA. 150u" TIN PLATING OVER NICKEL IN SOLDER AREA.
4. SHIELD :0.2mm THICKNESS COPPER ALLY WITH NICKEL . PLATEL

ELECTRICAL:

1. VOLTAGE PATING :125 VAC RMS.
2. CURRENT PATING :1.5 AMP
3. CONTACT RESISTANCE :30 MILLIOHMS MAX
4. INSULATION RESISTANCE:1000 MEGOHMS MIN @ 500V DC.
5. DIELECTRIC WITHSTANDING RESISTANCE: 1000V AC RMS 60HZ. 1MIN

MECHANICAL:

1. DURRABILITY :750 CYCLES MIN
2. PCB RETENTION PRE-SOLDER :10LB MIN

ENVIRONMENTAL:

1. STORAGE : -40°C TO +85°C .
2. OPERATION :0°C TO +70°C .
3. IR REFLOW SOLDERING TEMPERRATURE:255~265°C (5~10 SECONDS)MATES WITH MODULAR PLUG CONFORMING TO FCC PART 68 SUBPART F.

Order Code:

ATRJ5823 - 4P - 4C - X - A - X

① ② ③ ④ ⑤ ⑥

- ① SERIES NO:
- ② NUMBER OF POSITIONS (8P, 6P, 4P)
- ③ NUMBER OF CONTACTS (8C, 6C, 4C)
- ④ Contact Plating
G0:Gold flash
G1: 3U" Gold
G2: 5U" Gold
G3:10U" Gold
G4:15U" Gold
G5:30U" Gold
SN:Tin

- ⑤ Shield
A:W/O Shield
B:Half Shield
C:Shield W/Eml
D:Shield W/O Eml

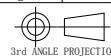
- ⑥ packing:
A: Tray packing
R: Tape & Reel

Unless Otherwise specified tolerance
X. ±0.35 X.XX: ±0.20
X.X: ±0.25 X.XXX: ±0.15

SCALE: As Shown UNIT: mm

DRAW Wu Feng Rong DATE 22/03/2018

CHECK BobYang DATE 22/03/2018



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TITLE:

TOP ENTRY SMT PCB JACK 4P

DRAWING NO: ATRJ5823-4P4C-X-A-X

PRODUCT NO: ATRJ5823-4P4C-X-A-X

REV	DESCRIPTION	DATE
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